



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-13
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BZW50-100B	8HVV*TWB121N	A	ZA41	2016-05-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	2050.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
RAD	27.8 - 8.5 - 8.5	2	Through-hole	
Comment	Package: R6			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HVV*TWB121N					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	24.524	mg	supplier	die	Silicon (Si)	7440-21-3		21.741	mg	886519	10605
				supplier	metallization	Aluminium (Al)	7429-90-5		2.333	mg	95131	1138
				supplier	Passivation	Silicon Oxide	7631-86-9		0.198	mg	8075	98
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.084	mg	3425	41
				supplier	back side metallization	Gold (Au)	7440-57-5		0.030	mg	1223	15
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.138	mg	5627	67
Leadframe	Copper & its alloys	1095.414	mg	supplier	alloy	Copper (Cu)	7440-50-8		1094.864	mg	999498	534080
				supplier	alloy	Zinc (Zn)	7440-66-6		0.046	mg	42	22
				supplier	alloy	Iron (Fe)	7439-89-6		0.109	mg	100	53
				supplier	alloy	Phosphorus (P)	12185-10-3		0.395	mg	361	193
Soft solder	Other organic materials	2.872	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.657	mg	925139	1296
				supplier	solder	Tin (Sn)	7440-31-5		0.144	mg	50139	70
				supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	24721	35
Encapsulation	Other organic materials	906.151	mg	supplier	mold compound	Silica fused(SiO2)	7631-86-9		362.463	mg	400003	176811
				supplier	mold compound	silica quartz	14808-60-7		521.037	mg	575000	254164
				supplier	mold compound	phenolic resin	9003-35-4		18.123	mg	20000	8840
				supplier	mold compound	carbon black	1333-86-4		4.528	mg	4997	2209
Connections coating	Solder	21.039	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		21.039	mg	1000000	10263